3132 AND 3133

ULTRA-SENSITIVE BIPOLAR HALL-EFFECT SWITCHES

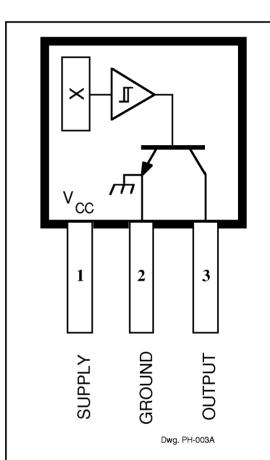
These Hall-effect switches are designed for magnetic actuation using a bipolar magnetic field, i.e., a north-south alternating field. They combine extreme magnetic sensitivity with excellent stability over varying temperature and supply voltage. The high sensitivity permits their use with multi-pole ring magnets over relatively large distances.

Each device includes a voltage regulator, quadratic Hall voltage generator, temperature stability circuit, signal amplifier, Schmitt trigger, and open-collector output on a single silicon chip. The on-board regulator permits operation with supply voltages of 4.5 to 24 volts. The switch output can sink up to 25 mA. With suitable output pull up, they can be used directly with bipolar or MOS logic circuits.

The four package styles available provide a magnetically optimized package for most applications. Suffix 'LT' is a surface-mount SOT-89 (TO-243AA) package; suffixes 'LL', 'U', and 'UA' feature wire leads for through-hole mounting. Prefix 'UGN' devices are rated for continuous operation over the temperature range of -20°C to +85°C; prefix 'UGS' devices over an extended range of -40°C to +125°C; prefix 'UGL' devices over the range of -40°C to +150°C.

FEATURES

- 4.5 V to 24 V Operation
- Reverse Battery Protection
- Superior Temperature Stability
- Superior Supply Voltage Stability
- Activate with Multi-Pole Ring Magnets
- Solid-State Reliability
- Small Size
- Constant Output Amplitude
- Resistant to Physical Stress



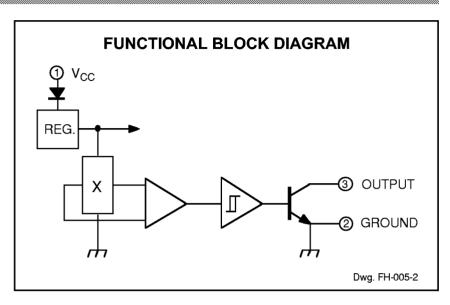
Pinning is shown viewed from branded side.

ABSOLUTE MAXIMUM RATINGS

Supply Voltage, V _{CC}
Reverse Battery Voltage, V _{RCC} 35 V
Magnetic Flux Density, B Unlimited
Output OFF Voltage, V _{OUT} 25 V
Continuous Output Current, I _{OUT} 25 mA
Operating Temperature Range, T _A
Prefix UGL40°C to +150°C
Prefix UGN20°C to +85°C
Prefix UGS40°C to +125°C
Storage Temperature Range,
T _S 65°C to +150°C

Always order by complete part number including prefix and suffix, e.g., **UGN3132LL**.





ELECTRICAL CHARACTERISTICS at T_A = +25°C

			Limits			
Characteristic	Symbol	Test Conditions	Min.	Тур.	Max.	Units
Supply Voltage	V _{CC}	Operating	4.5	_	24	V
Output Saturation Voltage	V _{OUT(SAT)}	$I_{OUT} = 20 \text{ mA}, B \ge B_{OP}$	_	145	400	mV
Output Leakage Current	l _{OFF}	V _{OUT} = 24 V, B ≤ B _{RP}	_	<1.0	10	μΑ
Supply Current	lcc	V _{CC} = 24 V, B ≤ B _{RP}	_	4.3	9.0	mA
Output Rise Time	t _r	$V_{CC} = 12 \text{ V}, R_L = 820 \Omega, C_L = 20 \text{ pF}$	_	0.04	2.0	μs
Output Fall Time	t _f	$V_{CC} = 12 \text{ V}, R_L = 820 \Omega, C_L = 20 \text{ pF}$		0.18	2.0	μs

MAGNETIC CHARACTERISTICS over operating temperature and voltage range.

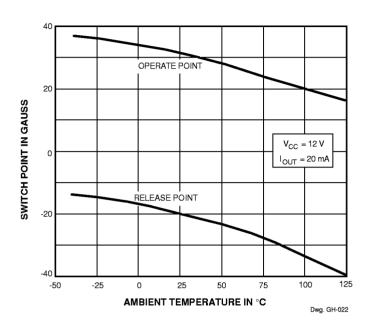
				Limits		
Characteristic	Symbol	Device Type*	Min.	Тур.	Max.	Units
Operate Point	B _{OP}	3132	_	32	95	G
		3133	_	32	75	G
Release Point	B _{RP}	3132	-95	-20	_	G
		3133	-75	-20	_	G
Hysteresis	B _{hys}	Both	30	52	_	G

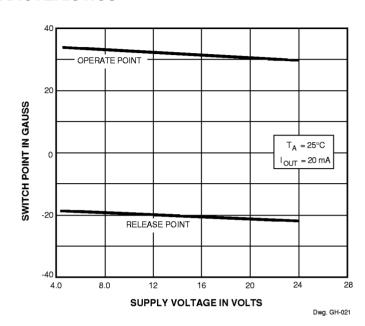
NOTE: As used here, negative flux densities are defined as less than zero (algebraic convention.) Typical values are at $T_A = +25^{\circ}C$ and $V_{CC} = 12 \text{ V}$.

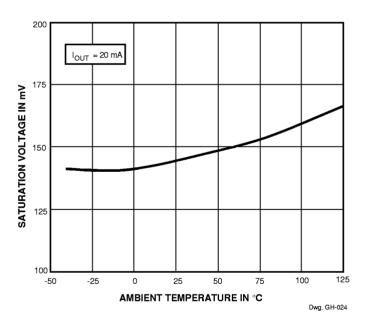
^{*} Complete part number includes a prefix denoting operating temperature range (UGL, UGN, or UGS) and a suffix denoting package type (LL, LT, U, or UA).

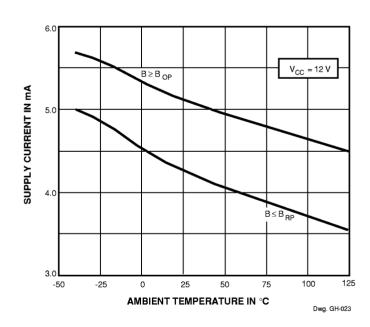


TYPICAL CHARACTERISTICS





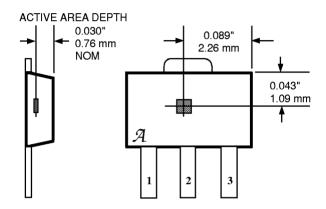




SENSOR LOCATIONS

(±0.005" [0.13mm] die placement)

SUFFIX "LL" & SUFFIX "LT"

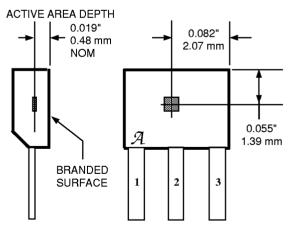


Dwg. MH-008-2C

SUFFIX "U"

ACTIVE AREA DEPTH 0.016" 0.41 mm NOM 2.31 mm 0.070" 1.78 mm BRANDED SURFACE 1 2 3

SUFFIX "UA"



Dwg. MH-011-10

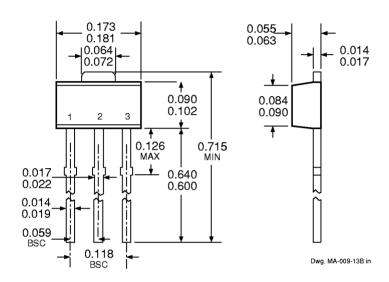


Dwg. MH-002-2B

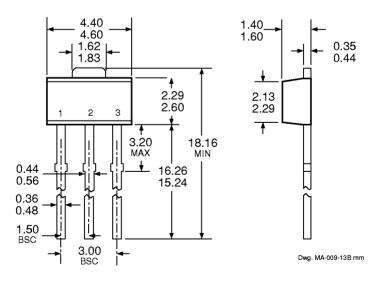
PACKAGE DESIGNATOR 'LL,

(Package 'LT' with long leads)

Dimensions in Inches (for reference only)



Dimensions in Millimeters (controlling dimensions)



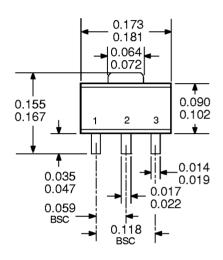
NOTES: 1. Tolerances on package height and width represent allowable mold offsets. Dimensions given are measured at the widest point (parting line).

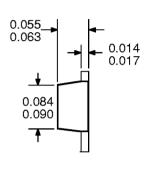
- 2. Exact body and lead configuration at vendor's option within limits shown.
- 3. Height does not include mold gate flash.

PACKAGE DESIGNATOR 'LT,

(SOT-89/TO-243AA)

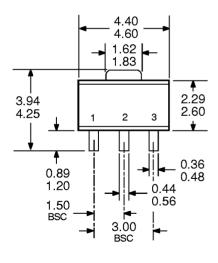
Dimensions in Inches (for reference only)

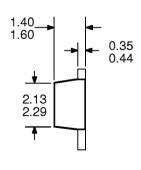




Dwg. MA-009-3 in

Dimensions in Millimeters (controlling dimensions)



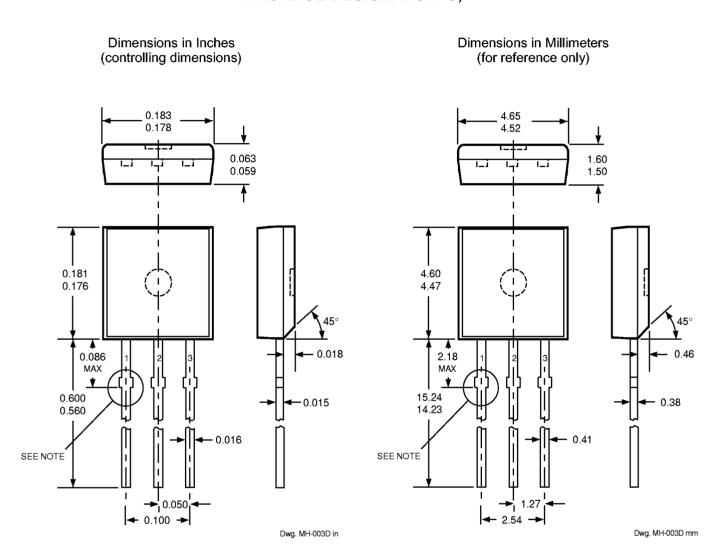


Dwg. MA-009-3 mm

- NOTES: 1. Tolerances on package height and width represent allowable mold offsets. Dimensions given are measured at the widest point (parting line).
 - 2. Exact body and lead configuration at vendor's option within limits shown.
 - 3. Height does not include mold gate flash.



PACKAGE DESIGNATOR 'U,



Devices in the 'U' package are NOT RECOMMENDED FOR NEW DESIGN

NOTES: 1. Tolerances on package height and width represent allowable mold offsets. Dimensions given are measured at the widest point (parting line).

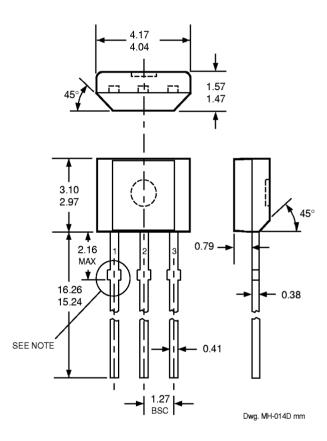
- 2. Exact body and lead configuration at vendor's option within limits shown.
- 3. Height does not include mold gate flash.
- 4. Recommended minimum PWB hole diameter to clear transition area is 0.035" (0.89 mm).
- 5. Where no tolerance is specified, dimension is nominal.

PACKAGE DESIGNATOR 'UA,

Dimensions in Inches (controlling dimensions)

0.164 0.159 0.062 0.058 0.085 0.085 0.085 0.085 0.085 0.085 0.085 0.095 0.095 0.0015

Dimensions in Millimeters (for reference only)



- NOTES: 1. Tolerances on package height and width represent allowable mold offsets.

 Dimensions given are measured at the widest point (parting line).
 - 2. Exact body and lead configuration at vendor's option within limits shown.
 - 3. Height does not include mold gate flash.
 - 4. Recommended minimum PWB hole diameter to clear transition area is 0.035" (0.89 mm).

Dwg. MH-014D in

5. Where no tolerance is specified, dimension is nominal.

BSC

Allegro MicroSystems, Inc. reserves the right to make, from time to time, such departures from the detail specifications as may be required to permit improvements in the design of its products.

The information included herein is believed to be accurate and reliable. However, Allegro MicroSystems, Inc. assumes no responsibility for its use; nor for any infringements of patents or other rights of third parties which may result from its use.

